

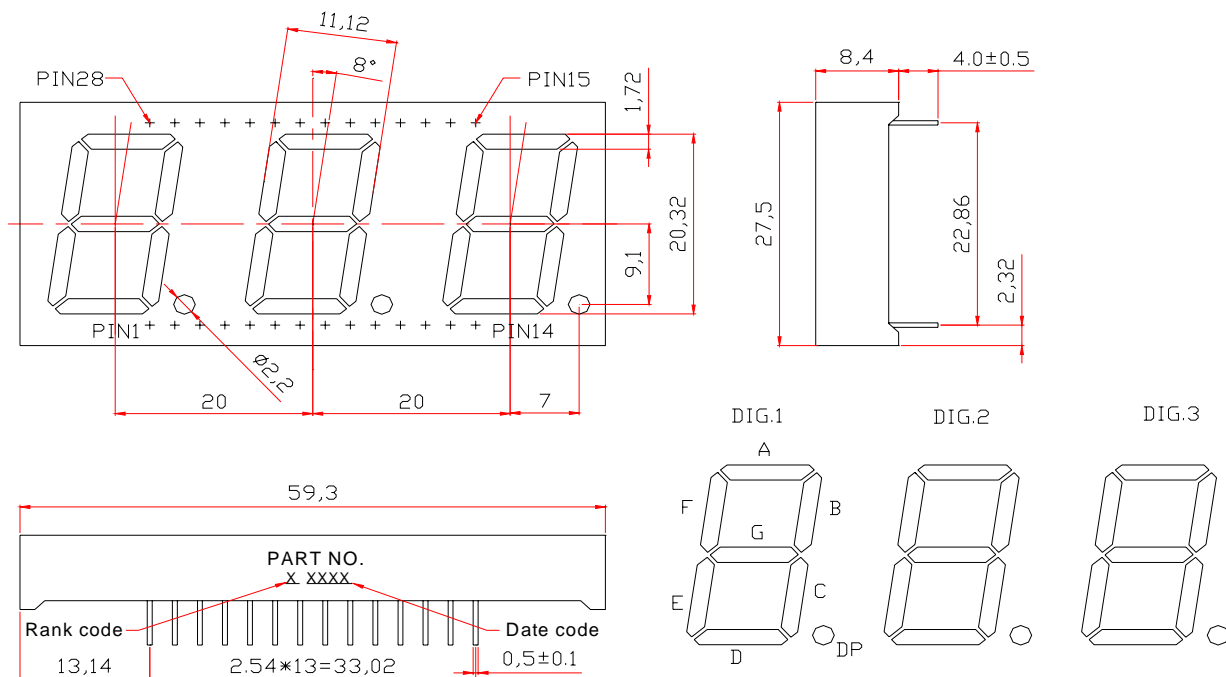
WCN3-0080R7-A81

SPECIFICATION

WCN			CUSTOMER Confirmed
Prepared by	Checked by	Approved by	
Fei 2017-05-23	Athena	William	
REVISION RECORD			

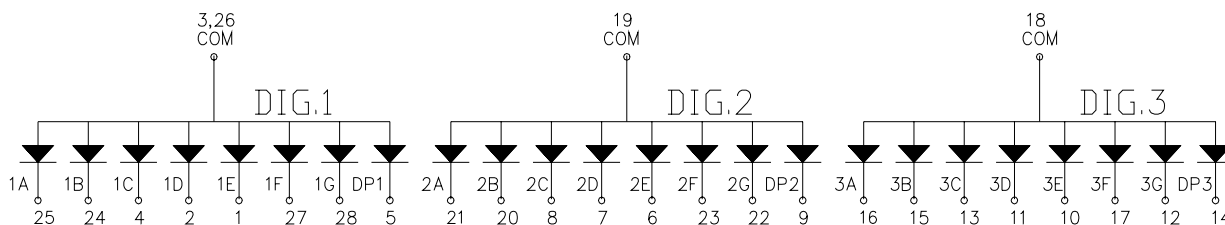
**REVISION: A0**

Outer Dimension:



Notes: Unless otherwise stated, The tolerance is $\pm 0.25\text{mm}$.

Circuit Diagram:



Pin Connection:

PIN NO.	CONNECTION	PIN NO.	CONNECTION	PIN NO.	CONNECTION
1	Cathode 1E	11	Cathode 3D	21	Cathode 2A
2	Cathode 1D	12	Cathode 3G	22	Cathode 2G
3	Common Anode DIG.1	13	Cathode 3C	23	Cathode 2F
4	Cathode 1C	14	Cathode DP3	24	Cathode 1B
5	Cathode DP1	15	Cathode 3B	25	Cathode 1A
6	Cathode 2E	16	Cathode 3A	26	Common Anode DIG.1
7	Cathode 2D	17	Cathode 3F	27	Cathode 1F
8	Cathode 2C	18	Common Anode DIG.3	28	Cathode 1G
9	Cathode DP2	19	Common Anode DIG.2	29	—
10	Cathode 3E	20	Cathode 2B	30	—

■ **Features:**

- High Reliability
- Color: Super bright Red
- Low Power Requirement
- Easy Assembly

■ **Description:**

- Three Digit Display
- Digit Height:20.4mm(0.8")
- Black Face and Milky Segment

■ **Absolute Maximum Rating (Ta=25°C):**

Parameter	Symbol	Condition	Color	Rating	Units
Power Dissipation Per Segment	P _d	—	Red	65	mW
Forward Current Per Segment	I _F	—	Red	25	mA
Peak Forward Current Per Segment	I _{FP}	1/10 Duty 10KHz	Red	100	mA
Reverse Voltage Per Segment	V _R	—	Red	5	V
Operating Temperature Range	T _{opr}	—	—	-35~+85	°C
Storage Temperature Range	T _{stg}	—	—	-35~+85	°C

■ **Electrical/Optical Characteristics Rating(Ta=25°C)**

Item	Symbol	Test conditions	Location	Rating			Units
				Min.	Typ.	Max.	
Forward Voltage	V _F	I _F =20mA	Per Segment	—	2.0	2.6	V
Reverse Current	I _R	V _R =5V	Per Segment	—	—	100	μA
Luminous Intensity	I _V	I _F =10mA	Per Segment	12801	19500	31000	μcd
Peak Emission Wave Length	λ _P	I _F =20mA	Per Segment	—	630	—	nm
	λ _D			620	623	627	
Spectral Line Half Width	△λ	I _F =20mA	Per Segment	—	20	—	nm
Luminous Intensity Matching Ratio (Segment to Segment)	I _{v-m}	I _F =10mA	—	—	—	1.2:1	

■ **Luminous Intensity Sorting: (Luminous Intensity Tolerance is +/-10%)**

Rank	Symbol	Condition	Min	Max	Unit
R	R	I _F =10mA	12801	15250	μcd
S	S	I _F =10mA	15251	18000	μcd
T	T	I _F =10mA	18001	21500	μcd
U	U	I _F =10mA	21501	26000	μcd
V	V	I _F =10mA	26001	31000	μcd

■ **Soldering Conditions: Soldering Temp. ≤+260°C, Soldering Time. ≤3sec.**
 (at 2mm Distance from The Case of Reflector Edge)

Typical Electro-Optical Characteristics Curve:

Fig 1. Forward Current vs. Forward Voltage

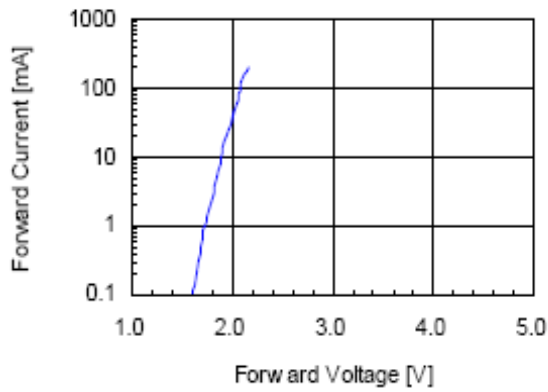


Fig 2. Relative Intensity vs. Forward Current

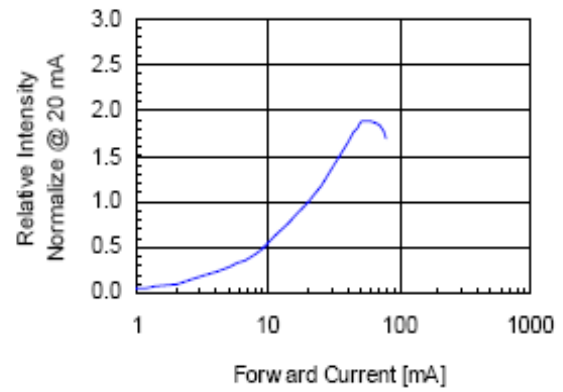


Fig 3. Forward Voltage vs. Temperature

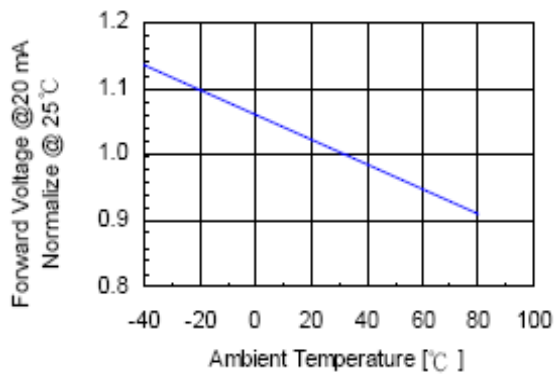


Fig 4. Relative Intensity vs. Temperature

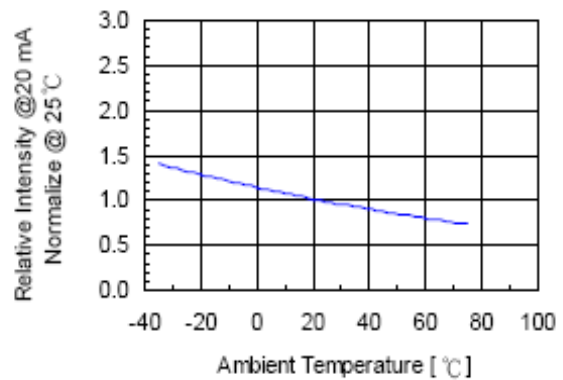
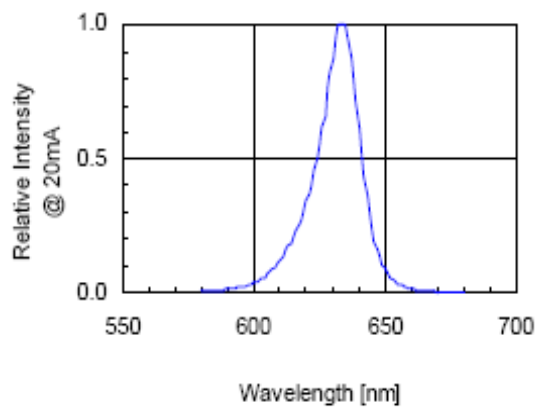


Fig 5. Relative Intensity vs. Wavelength



■ LED Displays Reliability Test:

CLASSIFICATION	TEST ITEM	DESCRIPTION AND TEST CONDITION
ENDURANCE TEST	OPERATION LIFE	EVALUATES RESISTANCE OF THE DEVICE WHEN OPERATED AT ELECTRICAL STRESS T_a = UNDER ROOM TEMPERATURE $I_F = I_F \text{ max}$
	HIGH TEMPERATURE HIGH HUMIDITY STORAGE	EVALUATES MOISTURE RESISTANCE OF THE DEVICE WHEN STORED FOR A LONG TERM AT HIGH TEMPERATURE AND HUMIDITY $T_a = 65 \pm 5^\circ\text{C}$ RH=90~95%RH TEST TIME=240± 2Hrs
	HIGH TEMPERATURE STORAGE	EVALUATES DEVICE DURABILITY FOR LONG TERM STORAGE IN HIGH TEMPERATURE $T_a = 85 \pm 5^\circ\text{C}$ (COB: $T_a = 65 \pm 5^\circ\text{C}$) TEST TIME=1000Hrs(-24Hrs, +72Hrs)
	LOW TEMPERATURE STORAGE	EVALUATES DEVICE DURABILITY FOR LONG TERM STORAGE IN LOW TEMPERATURE $T_a = -35 \pm 5^\circ\text{C}$ TEST TIME=1000Hrs(-24Hrs, +72Hrs)
ENVIRONMENTAL TEST	TEMPERATURE CYCLING	EVALUATES RESISTANCE OF DEVICE AT THERMAL STRESSES OR EXPANSION AND CONTRACTION $85^\circ\text{C} \sim 25^\circ\text{C} \sim -35^\circ\text{C} \sim 25^\circ\text{C}$ 30min 5min 30min 5min 10 CYCLES(COB: $T_{\text{hot}}=65^\circ\text{C}$, $T_{\text{cold}}=-25^\circ\text{C}$)
	THERMAL SHOCK	EVALUATES DEVICE STRUCTURE AND STRUCTURE AND MECHANICAL RESISTANCE WHEN SUDDENLY EXPOSED AT SERVE CHANGES $85 \pm 5^\circ\text{C} \sim -35 \pm 5^\circ\text{C}$ 10min 10min 10 CYCLES(COB: $T_{\text{hot}}=65^\circ\text{C}$, $T_{\text{cold}}=-25^\circ\text{C}$)
	SOLDERABILITY	EVALUATES SOLDERABILITY ON LEADS OF DEVICE $T_{\text{SOL}}=230 \pm 5^\circ\text{C}$ DWELL TIME=5±1sec.
	SOLDER RESISTANCE	EVALUATES RESISTANCE TO THERMAL STRESS CAUSED BY SOLDERING $T_{\text{SOL}}=260 \pm 5^\circ\text{C}$ DWELL TIME=10±1sec.

■ Packing method A:

25 pcs / Red Expandable Polyethylene.

150pcs / Box(360*175*130mm).

900 pcs / Carton(550*380*280mm).

■ Packing method B:

8 pcs / IC Tube.(520*37*21mm)

192 pcs / Box(537*175*125mm).

768 pcs / Carton(550*380*280mm).